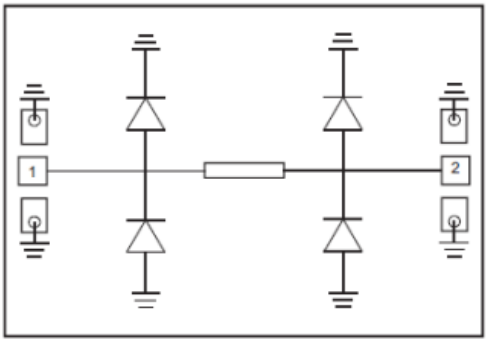
Features

- Frequency:1-6GHz
- Insertion Loss: 0.3dB（typ.)
- Limit Power:15dBm
- Tolerance Power:46dBm(CW)
- Input/Output: 50Ω
- Die Size: 1.92x1.22x 0.1 mm

Functional Block Diagram



Typical Applications

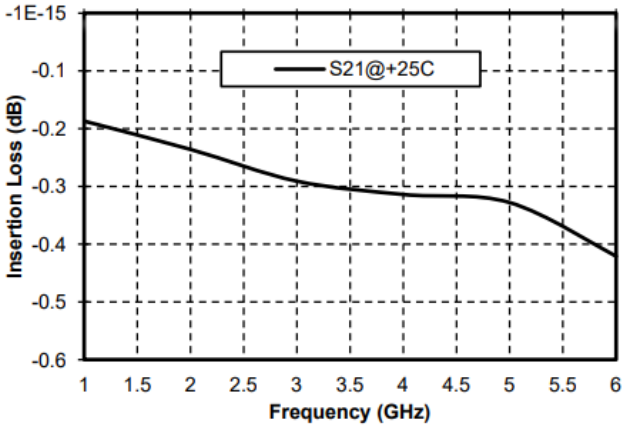
- Test Instrumentation
- Microwave Radio & VSAT
- Military & Space
- Telecom Infrastructure
- Fiber Optics

Electrical Specifications

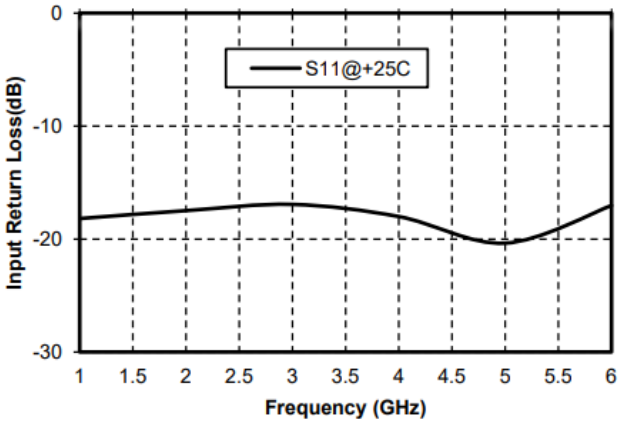
TA = +25ºC

Parameters	Min.	Typ.	Max.	Units
Frequency		1-6		GHz
Insertion Loss	-	0.3	0.4	dB
Input Return Loss	17	18	-	dB
Output Return Loss	17	20	-	dB
Limit Power	-	15	-	dBm
Tolerance Power		46		dBm

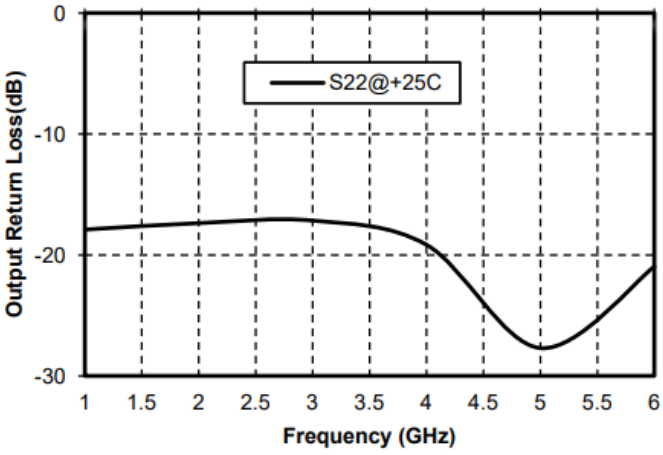
Insertion Loss Vs. Frequency



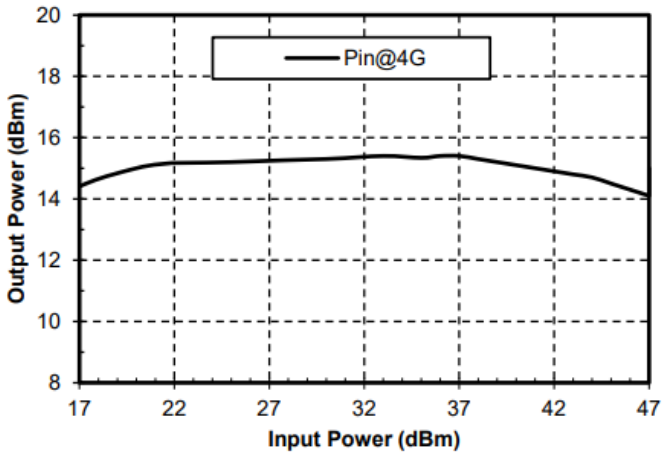
Input Return Loss Vs. Frequency



Output Return Loss Vs. Frequency

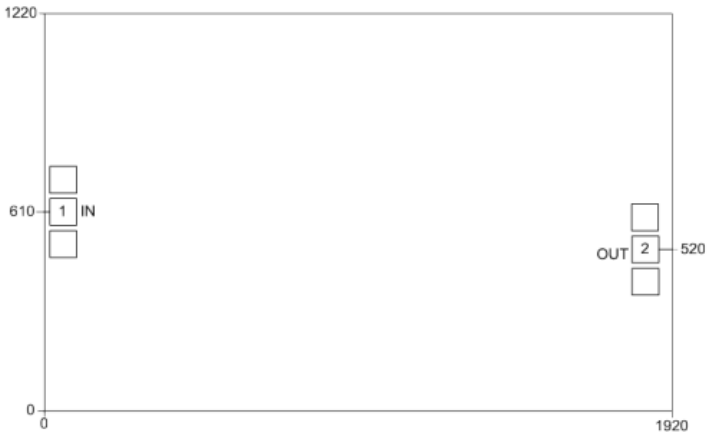


Limit Power @4G



Outline Drawing:

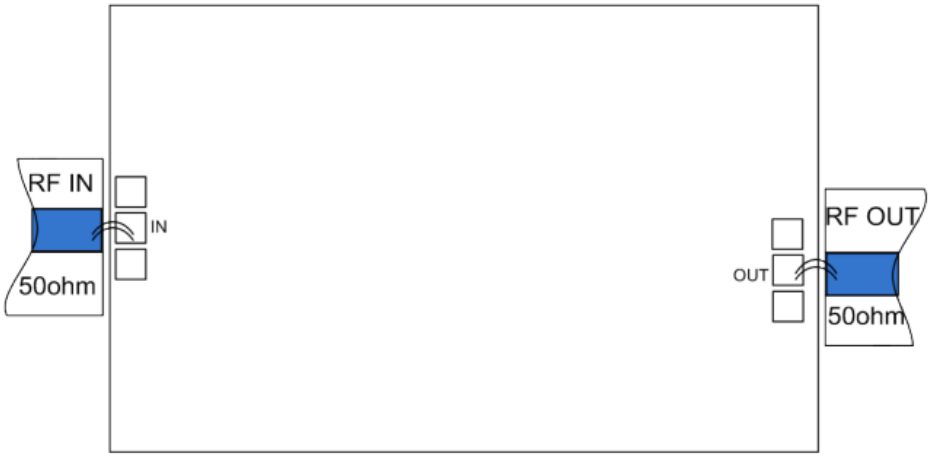
All Dimensions in um, tolerance range ±50um



Pad Description

PAD	Function	Description
1	RF IN	RF signal input, no DC blocking capacitor integrated at the chip input, external DC-blocking capacitor required
2	RF OUTPUT	RF signal output, A DC blocking capacitor has been integrated at the output of the chip
Die Bottom	GND	Die bottom must be connected to RF/DC ground.

Assembly Drawing



Notes:

1. Die thickness: 100um
2. Typical bond pad is 100*100 μm^2
3. Bond pad metalization: Gold
4. Backside metalization: Gold
5. Backside of the die (GND)
6. No connection required for unlabeled bond pads

Maximum Ratings:

1. RF input power: +46dBm
2. Storage temperature: -65℃ to +150℃
3. Operating temperature: -55℃ to 125℃